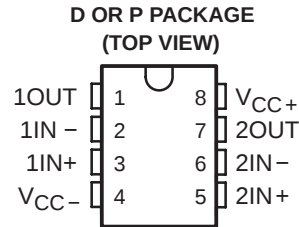


LF412C DUAL JFET-INPUT OPERATIONAL AMPLIFIER

SLOS010B – MARCH 1987 – REVISED AUGUST 1994

- Low Input Bias Current . . . 50 pA Typ
- Low Input Noise Current
0.01 pA/√Hz Typ
- Low Supply Current . . . 4.5 mA Typ
- High Input impedance . . . $10^{12} \Omega$ Typ
- Internally Trimmed Offset Voltage
- Wide Gain Bandwidth . . . 3 MHz Typ
- High Slew Rate . . . 13 V/μs Typ



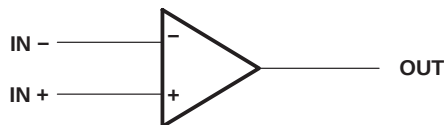
description

This device is a low-cost, high-speed, JFET-input operational amplifier with very low input offset voltage and a specified maximum input offset voltage drift. It requires low supply current yet maintains a large gain bandwidth product and a fast slew rate. In addition, the matched high-voltage JFET input provides very low input bias and offset currents.

The LF412C can be used in applications such as high-speed integrators, digital-to-analog converters, sample-and-hold circuits, and many other circuits.

The LF412C is characterized for operation from 0°C to 70°C.

symbol (each amplifier)



AVAILABLE OPTIONS

T _A	V _{IO} max AT 25°C	PACKAGE	
		SMALL OUTLINE (D)	PLASTIC DIP (P)
0°C to 70°C	3 mV	LF412CD	LF412CP

The D packages are available taped and reeled. Add the suffix R to the device type (ie., LF412CDR).

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} +	18 V
Supply voltage, V _{CC} -	-18 V
Differential input voltage, V _{ID}	±30 V
Input voltage, V _I (see Note 1)	±15 V
Duration of output short circuit	unlimited
Continuous total power dissipation	500 mW
Operating temperature range	0°C to 70°C
Storage temperature range	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

NOTE 1: Unless otherwise specified, the absolute maximum negative input voltage is equal to the negative power supply voltage.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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LF412C

DUAL JFET-INPUT OPERATIONAL AMPLIFIER

SLOS010B – MARCH 1987 – REVISED AUGUST 1994

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{CC+}	3.5	18	V
Supply voltage, V_{CC-}	-3.5	-18	V

electrical characteristics over operating free-air temperature range, $V_{CC\pm} = \pm 15$ V (unless otherwise specified)

PARAMETER	TEST CONDITIONS	T_A †	MIN	TYP	MAX	UNIT
V_{IO} Input offset voltage	$V_{IC} = 0$, $R_S = 10\text{ k}\Omega$	25°C		1	3	mV
α_{VIO} Average temperature coefficient of input offset voltage	$V_{IC} = 0$, $R_S = 10\text{ k}\Omega$			10	20‡	$\mu\text{V}/^\circ\text{C}$
I_{IO} Input offset current§	$V_{IC} = 0$	25°C		25	100	pA
		70°C			4	nA
I_{IB} Input bias current§	$V_{IC} = 0$	25°C		50	200	pA
		70°C			8	nA
V_{ICR} Common-mode input voltage range			± 11	-11.5 to 14.5		V
V_{OM} Maximum peak output voltage swing	$R_L = 10\text{ k}\Omega$		± 12	± 13.5		V
A_{VD} Large-signal differential voltage	$V_O = \pm 10\text{ V}$, $R_L = 2\text{ k}\Omega$	25°C	25	200		V/mV
		Full range	15	200		
r_i Input resistance	$T_A = 25^\circ\text{C}$			10^{12}		Ω
CMRR Common-mode rejection ratio	$R_S \leq 10\text{ k}\Omega$		70	100		dB
k_{SVR} Supply-voltage rejection ratio	See Note 2		70	100		dB
I_{CC} Supply current				4.5	6.8	mA

† Full range is 0°C to 70°C.

‡ At least 90% of the devices meet this limit for α_{VIO} .

§ Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques must be used that will maintain the junction temperatures as close to the ambient temperature as possible.

NOTE 2: Supply-voltage rejection ratio is measured for both supply magnitudes increasing or decreasing simultaneously.

operating characteristics, $V_{CC\pm} = \pm 15$ V, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{O1}/V_{O2} Crosstalk attenuation	$f = 1\text{ kHz}$		120		dB
SR Slew rate		8	13		V/ μs
B_1 Unity-gain bandwidth		2.7	3		MHz
V_n Equivalent input noise voltage	$f = 1\text{ kHz}$, $R_S = 20\text{ }\Omega$		18		$\text{nV}/\sqrt{\text{Hz}}$
I_n Equivalent input noise current	$f = 1\text{ kHz}$		0.01		$\text{pA}/\sqrt{\text{Hz}}$



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LF412 MWC	Active	Production	WAFERSALE (YS) 0	1 NOT REQUIRED	-	Call TI	Level-1-NA-UNLIM	-40 to 85	
LF412CD	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	0 to 70	LF412C
LF412CDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LF412C
LF412CDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LF412C
LF412CDR1G4	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LF412C
LF412CDR1G4.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LF412C
LF412CDRE4	Active	Production	SOIC (D) 8	2500 LARGE T&R	-	Call TI	Call TI	0 to 70	
LF412CDRG4	Active	Production	SOIC (D) 8	2500 LARGE T&R	-	Call TI	Call TI	0 to 70	
LF412CP	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	LF412CP
LF412CP.A	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	LF412CP

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

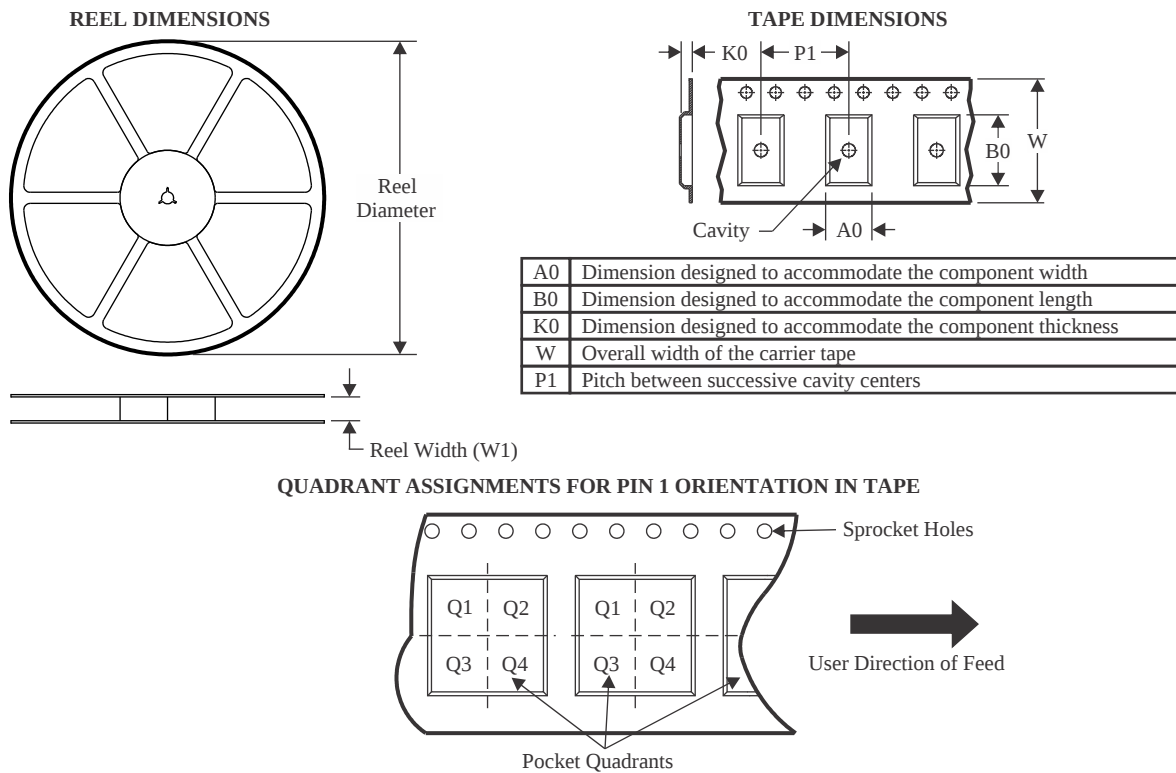
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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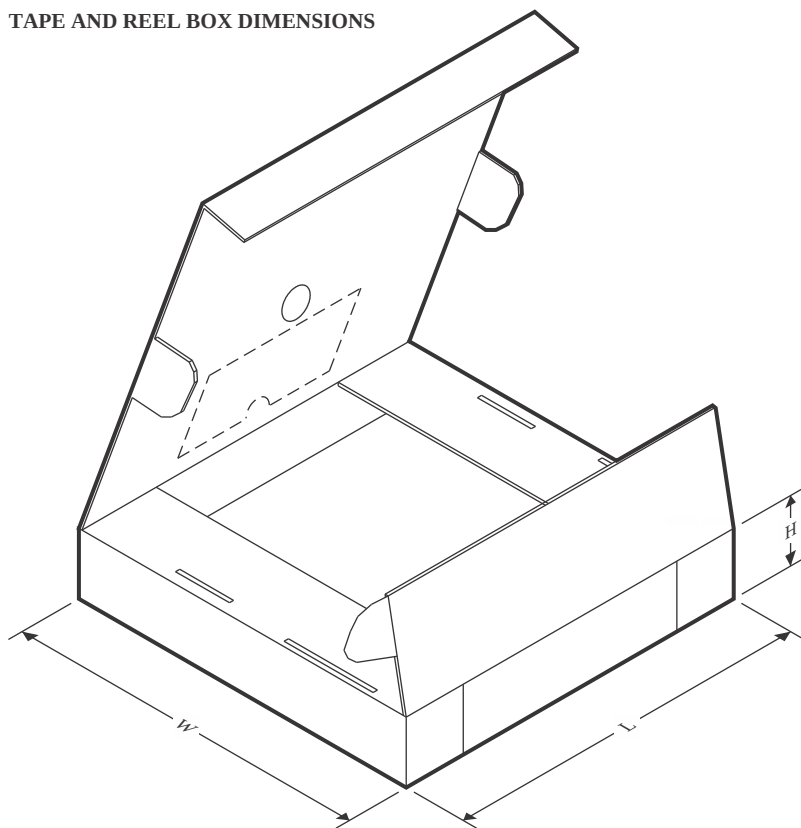
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LF412CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LF412CDR1G4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LF412CDR	SOIC	D	8	2500	353.0	353.0	32.0
LF412CDR1G4	SOIC	D	8	2500	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
LF412CP	P	PDIP	8	50	506	13.97	11230	4.32
LF412CP.A	P	PDIP	8	50	506	13.97	11230	4.32



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



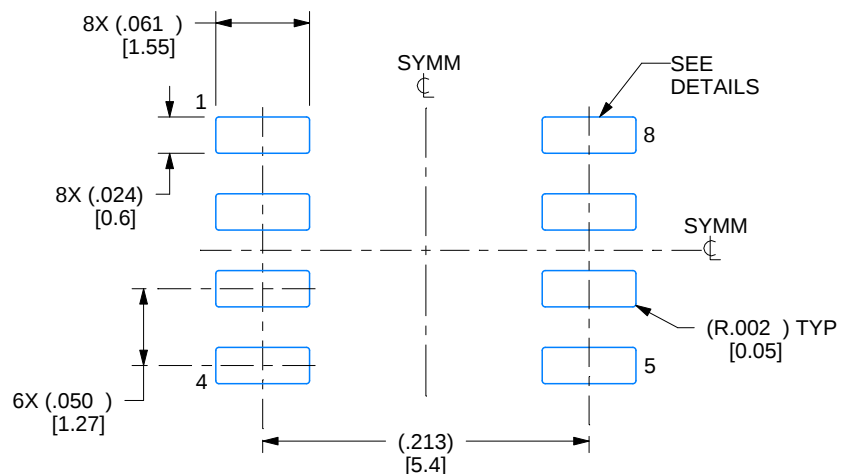
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

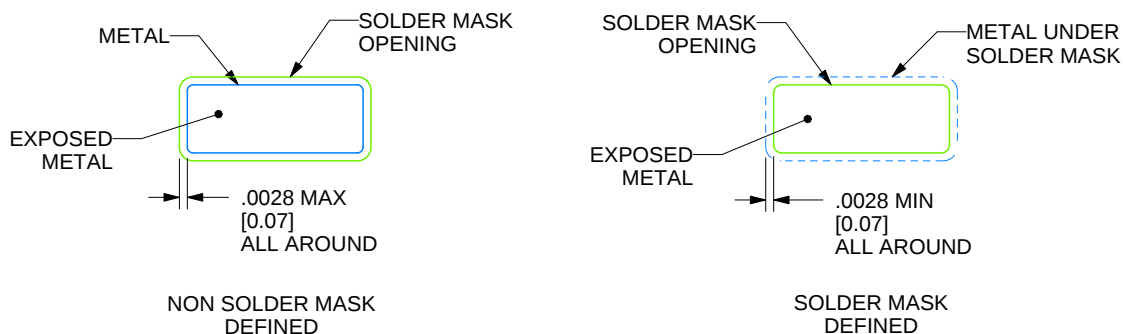
D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

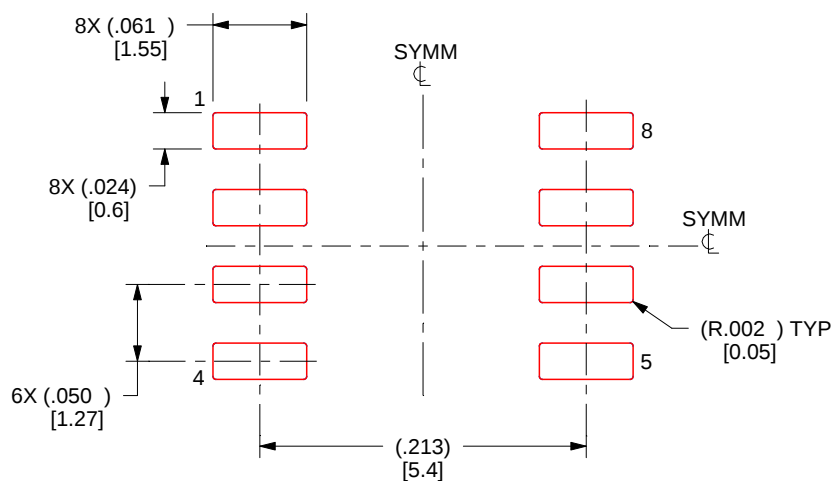
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

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